


**Form 1449 (Modified)**
**Information Disclosure  
Statement By Applicant**

(Use Several Sheets if Necessary)

 Atty Docket No.  
LAM1P147/P0675

 Application No.:  
09/782,185

 Applicant:  
ZHU et al.

 Filing Date  
February 12, 2001

 Group  
3765

**U.S. Patent Documents**

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A						
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

**Foreign Patent or Published Foreign Patent Application**

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

**Other Documents**

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication		
K-cc	O	U.S. Patent Application Serial No. 09/782,678, entitled "Post-Etch Photoresist Strip with O2 and NH3 for Organosilicate Glass Low-K Dielectric Etch Applications", filed February 12, 2001		
K-cc	P	U.S. Patent Application Serial No. 09/782,446, entitled "Use of Ammonia for Etching Organic Low-K Dielectrics", filed February 12, 2001		
K-cc	Q	U.S. Patent Application Serial No. 09/782,437, entitled "Use of Hydrocarbon Addition for the Elimination of Micromasking during Etching of Organic Low-K Dielectrics", filed February 12, 2001		

Examiner

*Kin-CL MENG*

Date Considered

*02-19-02*

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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